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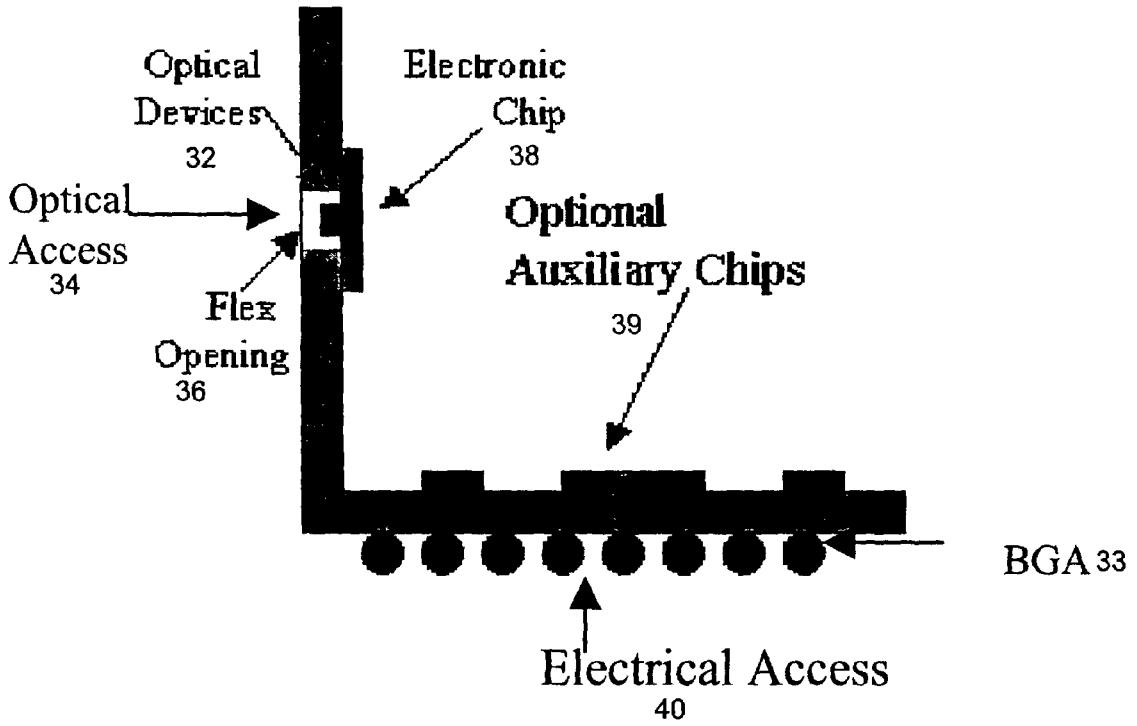
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[Continued on next page]

(54) Title: OPTICAL CHIP PACKAGING VIA THROUGH HOLE



(57) Abstract: A method of packaging an optical or an optical chip (32) with an electronic chip (38) that allows for close connections between the two chips. The method reduces parasitic capacitance and inductance, and provides unobstructed optical access while allowing for connection of a heat sink to the electronic chip for cooling.

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